

L Number	Hits	Search Text	DB	Time stamp
23	248	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same (plat\$6 electroplat\$6 electroless)) and (((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp)) same (organic adhe\$8 peel\$6 resist photoresist paste))	USPAT; US-PGPUB	2004/08/04 08:19
24	81	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same ((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))) same (plat\$6 electroplat\$6 electroless)	USPAT; US-PGPUB	2004/08/04 09:55
25	43	(438/667.ccls 257/621.ccls.) and (438/458.ccls. 438/459.ccls. 438/672.ccls. 438/675.ccls. 438/928.ccls. 438/977.ccls. 257/774.ccls.)	USPAT; US-PGPUB	2004/08/04 10:34
27	4	ep-926723-\$.did. ep-1151962-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/04 10:35
26	190	438/667.ccls 257/621.ccls.	USPAT; US-PGPUB	2004/08/04 10:37
35	4	("5424245" "5946600" "6331208" "6605551" "2003/0082851" "2003/0203623").PN.	USPAT	2004/08/04 12:13
38	8	("3969745" "3986196" "4403241" "4445978" "4752555" "4842699" "4978639" "5053318").PN.	USPAT	2004/08/04 12:17
39	4	5260169.URPN.	USPAT	2004/08/04 12:20
44	15	("2770761" "3895967" "3897361" "3904442" "3979820" "4074342" "4239312" "4275410" "4370179" "4535424" "4660066" "4720308" "4761681" "4773972" "4860084").PN.	USPAT	2004/08/04 12:21
45	30	5528080.URPN.	USPAT	2004/08/04 12:27
49	4	("5243498" "5434094" "5488253" "5646067").PN.	USPAT	2004/08/04 12:33
50	1	6365513.URPN.	USPAT	2004/08/04 12:38
53	11	("3323198" "3484341" "3562009" "4089992" "4153988" "4211603" "4348253" "4403241" "4426767" "4467521" "4512829").PN.	USPAT	2004/08/04 12:45
54	38	4978639.URPN.	USPAT	2004/08/04 12:46
57	46	("3171762" "3256465" "3343256" "3372070" "3418545" "3445686" "3454835" "3456335" "3462650" "3648131" "3761782" "3796927" "3798513" "3885196" "3959579" "3962052" "3969745" "3982268" "4074342" "4097890" "4104674" "4188709" "4263341" "4275410" "4368503" "4379307" "4467343" "4528072" "4613891" "4670764" "4720738" "4761681" "4765864" "4839309" "4839510" "4862322" "4897708" "4954875" "4978639" "5024966" "5166097" "5198698" "5268326" "5322816" "5420064" "5443661").PN.	USPAT USPAT	2004/08/04 12:52
58	84	5646067.URPN.	USPAT	2004/08/04 12:57
67	27	5618752.URPN.	USPAT	2004/08/04 12:59
68	45	("3171762" "3256465" "3343256" "3372070" "3418545" "3445686" "3454835" "3456335" "3462650" "3648131" "3761782" "3796927" "3798513" "3885196" "3959579" "3962052" "3969745" "3982268" "4074342" "4097890" "4104674" "4188709" "4263341" "4275410" "4368503" "4379307" "4467343" "4528072" "4613891" "4670764" "4720738" "4761681" "4765864" "4839309" "4839510" "4862322" "4897708" "4954875" "4978639" "5024966" "5166097" "5198695" "5268326" "5322816" "5420064").PN.	USPAT	2004/08/04 13:01

73	10	("3648131" "4754316" "4761681" "4807021" "4954875" "5037782" "5059553" "5139969" "5229647" "5366589").PN.	USPAT	2004/08/04 13:02
74	63	5424245.URPN.	USPAT	2004/08/04 13:03
-	4	jp-2001326326-\$.did. jp-10074891-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/03 15:33
-	4848	438/458.ccls. 438/459.ccls. 438/667.ccls. 438/672.ccls. 438/675.ccls. 438/928.ccls. 438/977.ccls. 257/621.ccls. 257/774.ccls.	USPAT; US-PGPUB	2004/08/04 10:11
-	22013	(electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))	USPAT; US-PGPUB	2004/08/03 15:40
-	32009	(electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 15:41
-	1818	((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) and ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp))	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:18
-	360	((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) and ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp))) and (plat\$6 electroplat\$6 electroless)	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:19
-	1004	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp))	USPAT; US-PGPUB	2004/08/03 17:21
-	169	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp))) same (plat\$6 electroplat\$6 electroless)	USPAT; US-PGPUB	2004/08/03 15:51
-	4338	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same (plat\$6 electroplat\$6 electroless)	USPAT; US-PGPUB	2004/08/03 17:22
-	1082	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same (plat\$6 electroplat\$6 electroless) and ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp)) and (organic adhe\$8 peel\$6 resist photoresist paste)	USPAT; US-PGPUB	2004/08/03 15:52
-	531	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same (plat\$6 electroplat\$6 electroless) and (((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp)) same (organic adhe\$8 peel\$6 resist photoresist paste))	USPAT; US-PGPUB	2004/08/03 17:20
-	356	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same (plat\$6 electroplat\$6 electroless) and (((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp)) with (organic adhe\$8 peel\$6 resist photoresist paste))	USPAT; US-PGPUB	2004/08/03 15:55
-	39	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp))) same (plat\$6 electroplat\$6 electroless)	USPAT; US-PGPUB	2004/08/03 15:57
-	100	same (organic adhe\$8 peel\$6 resist photoresist paste) (438/458.ccls. 438/459.ccls. 438/667.ccls. 438/672.ccls. 438/675.ccls. 438/928.ccls. 438/977.ccls. 257/621.ccls. 257/774.ccls.) and (electrode near2 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))	USPAT; US-PGPUB	2004/08/03 16:26

-	110	(((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) and ((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp))) and (plat\$6 electroplat\$6 electroless)) and (organic adhe\$8 peel\$6 resist photoresist paste)	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:04
-	1532	((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) and ((wafer substrate) with (thin\$6 grind\$6 polish\$6 etch\$6 cmp))	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:19
-	903	((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) and ((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:19
-	521	((electrode near4 (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) same ((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))	USPAT; US-PGPUB	2004/08/03 17:22
-	163	(((electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole "through-hole" (through adj hole)))) and ((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))) and (plat\$6 electroplat\$6 electroless)	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:01